### RTX-113HV

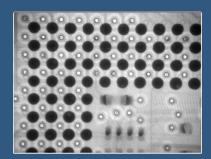
# Designed for inspection of multi-layer and assembled printed circuit boards with dense metal BGAs



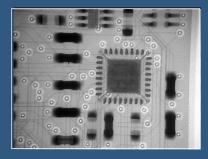
Our RTX-113HV system meets all your needs for inspecting BGA packages, including those that contain dense metal heat sinks that require a higher voltage X-ray source to clearly identify and troubleshoot production faults. The cabinet design permits easy integration into even the busiest production environments, and is totally upgradeable. Recommended for lead free inspection requirements.



# Real-Time X-ray Microscope Inspection Exposes Hidden BGA Flaws



**BGA** Inspection



QFN Inspection



Cable Inspection



Multilayer PC Board Inspection

#### **Specifications**

- 50"H x 60"W x 33"D (1270mm x 1524mm x 839mm)
- Operating Voltage: 120v/220v, 50-60hz
- Contrast Resolution: Can resolve .001 gold wire
- Spatial Resolution: 20 lp/mm (with MicroTech<sup>TM</sup> option, up to 100 lp/mm) Anode Voltage: 80 kV
- Anode Current: 150 microamps
- Focal Spot to Image Plane Distance: 4-6 inches
- XRTV Zoom Camera (4X-50X magnification)

#### **Options**

- PC Based Image Processing with BGA and Void Measurement software
- MicroTechTM 10-micron X-ray Source (225X) Motorized X-Y positioner
- Variable Angle Viewing allowing 45 degree viewing

